



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-04-09
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HVWV*UT92AA6	A	ZS1A	2015-04-09
Amount	UoM	Unit type	ST ECOPACK Grade	
17.10	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.8 - 1.5 - 0.9	5	gull wing	
Comment	Package: SOT 23 5L; MDF valid for LD3985M18R			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HVWV*UT92AA6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	0.868	mg	supplier	die	Silicon (Si)	7440-21-3		0.833	mg	959677	48713	
die (s)				supplier	metallization	Aluminum (Al)	7429-90-5		0.007	mg	8065	409	
die (s)				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.002	mg	2304	117	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	19585	994	
die (s)				supplier	polymer die coating	PIXI Gamma-butylolactone	96-48-0		0.009	mg	10369	526	
Leadframe	Copper & its alloys	7.198	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.934	mg	963323	405497	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.162	mg	22506	9474	
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	278	117	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1250	526	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	11531	4854	
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	972	409	
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	139	58	
Die attach	Other Organic Materials	0.068	mg	supplier	glue	Silver (Ag)	7440-22-4		0.047	mg	691176	2749	
Die attach				supplier	glue	methylene diacrylate	42594-17-2		0.017	mg	250000	994	
Die attach				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.002	mg	29412	117	
Die attach				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.002	mg	29412	117	
Bonding wire	Precious metals	0.15	mg	supplier	wire	Gold (Au)	7440-57-5		0.15	mg	1000000	8772	
Encapsulation	Other Organic Materials	8.816	mg	supplier	molding compound	Silica, vitreous	60676-86-0		7.52	mg	852995	439766	
Encapsulation				supplier	molding compound	phenolic resin	Proprietary		0.308	mg	34936	18012	
Encapsulation				supplier	molding compound	epoxy resin	Proprietary		0.353	mg	40041	20643	
Encapsulation				supplier	molding compound	Biphenyl epoxy resin	85954-11-6		0.176	mg	19964	10292	
Encapsulation				supplier	molding compound	carbon black	1333-86-4		0.018	mg	2042	1053	
Encapsulation				supplier	molding compound	Zinc hydroxide	20427-58-1		0.088	mg	9982	5146	
Encapsulation				supplier	molding compound	Magnesium hydroxide	1309-42-8		0.353	mg	40041	20643	